

CRYSTAL OSCILLATOR **PROGRAMMABLE**

SG-8002 series

•Frequency range : 1 MHz to 125 MHz •Supply voltage : 3.0 V/3.3 V/5.0 V

Function : Output enable(OE) or Standby(ST)

•Short mass production lead time by PLL technology.

•SG-Writer available to purchase,

please contact Epson Toyocom or local sales representative.



Specifications (characteristics)

Item	Symbol		Specifications *2		Conditions / Remarks	
ILGIII	Cyllibol	PT / ST	PH/SH	PC / SC		
		1 MHz	to 125 MHz	_	Vcc = 4.5 V to 5.5 V (except SG-8002LB)	
Output frequency range	fo	_	1 MHz to 80 MHz	_	Vcc = 4.5 V to 5.5 V (SG-8002LB only)	
Catput requerity range	10	_	_		Vcc = 3.0 V to 3.6 V	
	.,				Vcc = 2.7 V to 3.6 V	
Supply voltage	Vcc		/ to 5.5 V	2.7 V to 3.6 V		
		-55 °C to +125 °C (SG-8002CA / JF / JA / DC / DB)			Store as bare product.	
Storage temperature	T_stg	-55 °C to +100 °C (SG-8002JC) -40 °C to +125 °C (SG-8002CE / LB)				
	-				**	
Operating temperature	T_use		C to +70 °C / -40 °C		*1	
Francisco de la recesa	£ 4-1		: ±50 × 10 ⁻⁶ , C: ±100		-20 °C to +70 °C	
Frequency tolerance	f_tol	M: ±'	100 × 10 ⁻⁶	M: ±100 × 10 ⁻⁶	-40 °C to +85 °C (except SG-8002JC) *3	
			L:±50 × 10 ⁻⁶	L:±50 × 10 ⁻⁶	-40 °C to +85 °C (SG-8002LB only) *3	
		40 mA Max	(. (SG-8002CE)			
Current consumption	Icc	_	30 mA Max. (SG-8002LB)	28 mA Max.	No load condition, Max. frequency	
Current consumption	100	15.	mA Max.	20 IIIA Wax.	ino load condition, max. frequency	
		(SG-8002CA / JF /JC / JA / DC / DB) 30 mA Max. 16 mA Max.		16 mA Max.	OE=GND (PT.PH,PC) (except SG-8002LB)	
Output disable current	I_dis	_	25 mA Max.	16 mA Max.	OE=GND (PH,PC) (SG-8002LB only)	
Stand-by current	I_std		50 μA Max.		ST =GND (ST,SH,SC)	
		40 % to 60 %		_	TTL load: 1.4 V, Max. load condition (except SG-8002LB)	
		— 40 % to 60 %		22.24	CMOS load:50 % VCC level, Max. load condition	
				0 60 %	(except SG-8002LB)	
Symmetry *1	SYM	_	40 % to 60 %	_	50 % Vcc, L_CMOS=15 pF, ≤80 MHz (SG-8002LB)	
Symmetry	STW	_	_	40 % to 60 %	50 % Vcc, L_CMOS=15 pF, Vcc=3.0 V to 3.6 V, \leq 125 MHz (SG-8002LB)	
		_	_	40 % to 60 %	50 % Vcc, L_CMOS=15 pF, Vcc=2.7 V to 3.6 V, ≤66.7 MHz (SG-8002LB)	
		45 % to 55 %			*1	
High output voltage	Voн		Vcc -0.4 V Min.		IOH=-16 mA (PT,ST,PH,SH) , -8 mA (PC,SC)	
Low output voltage	Vol		0.4 V Max.		IOL=16 mA (PT,ST,PH,SH) , 8 mA (PC,SC)	
Output load condition	L_TTL	5 TTL Max. —		_	Max. frequency and Max. Supply voltage (SG-8002CE / CA / JA / DC / DB)	
(TTĹ) *1		5 TTL Max. —		_	f0 ≤ 90 MHz and Max. Supply voltage (SG-8002JF / JC)	
	L_CMOS	15 pF Max.			Max. frequency and Max. Supply voltage (SG-8002CE / JF / JC)	
Output load condition (CMOS) *1		— 15 pF Max.		Max.	Max. frequency and Max. Supply voltage (SG-8002LB)	
		15 pF Max.	25 pF Max	15 pF Max.	Max. frequency and Max. Supply voltage (SG-8002CA / JA / DC / DB)	
Output enable /	VIH	2.0	0 V Min. 70 % VCC Min.		i i	
disable input voltage	VIL	0.8 V Max. 20 % VCC Max.		20 % VCC Max.	OE terminal or ST terminal	
Rise / Fall time *1	tr/ tf	4 ns Max. —		_	TTL load: 0.4 V to 2.4 V level (except SG-8002LB)	
TAIGG / T AII WITHE ' I	u/ u	3 ns Max.		Max.	CMOS load: 20 % VCC to 80 % VCC level	
Start-up time	t_str		10 ms Max.		Time at minimum supply voltage to be 0 s	
Frequency aging	f_aging		±5 × 10 ⁻⁶ / year Max.		+25 °C, VCC=5.0 V/ 3.3 V (PC,SC) First year	

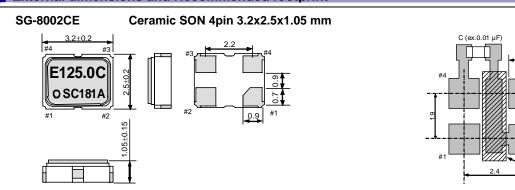
Operating temperature, the available frequency, symmetry, output load conditions and rise/fall time, please refer to "Outline specifications" page.
 PLL-PLL connection & Jitter specification, please refer to "Jitter specifications and characteristics chart" page.

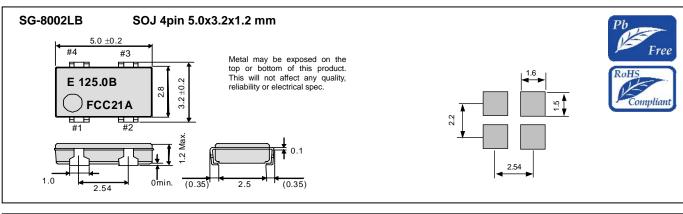
Refer to "Outline specifications" (Frequency range) for "M" and "L" tolerance availability. Checking possible by the Frequency checking program.

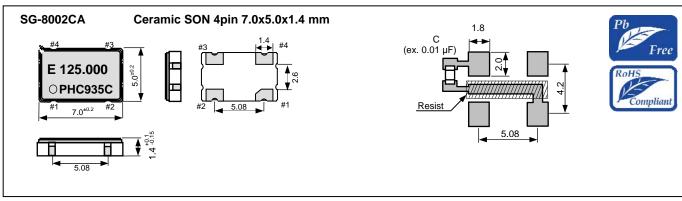
External dimensions and Recommended footprint

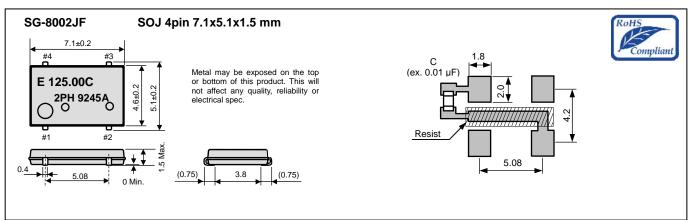
(Unit:mm)

Complian









Note

OE Pin (PT, PH, PC)

OE Pin = "H" or "open": Specified frequency output.

OE Pin = "L": Output is high impedance.

ST Pin (ST, SH, SC)

 $\overline{\text{ST}}$ Pin = "H" or "open": Specified frequency output.

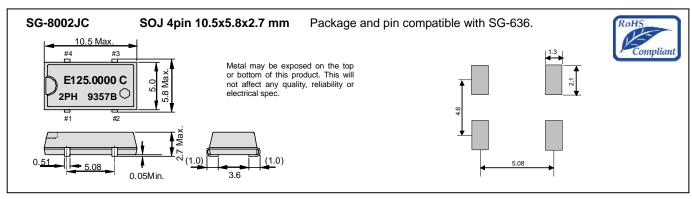
 $\overline{\text{ST}} \;\; \text{Pin} = \text{"L"} : \text{Output} \; \text{is low level (weak pull - down), oscillation stops.}$

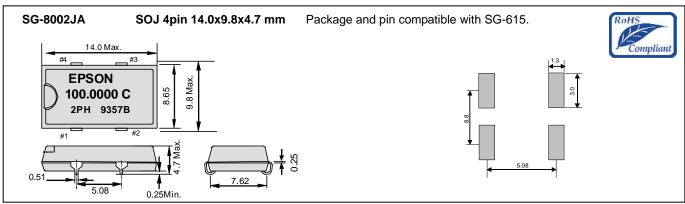
F	Pin ma	р
	Pin	Connection
	1	OE or ST
	2	GND
	3	OUT
	4	VCC

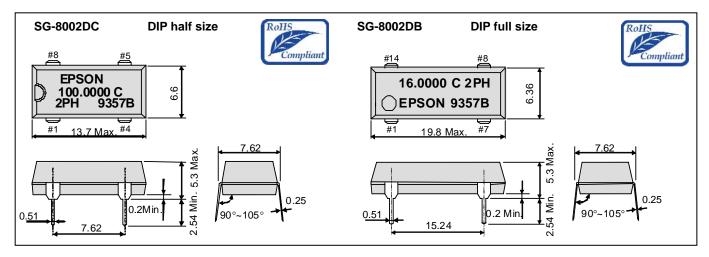
To maintain stable operation, provide a 0.01uF to 0.1uF by-pass capacitor at a location as near as possible to the power source terminal of the crystal product (between Vcc - GND).

External dimensions and Recommended footprint (Continued)

(Unit:mm)







Note.

OE Pin (PT, PH, PC)

OE Pin = "H" or "open": Specified frequency output.

OE Pin = "L": Output is high impedance.

ST Pin (ST, SH, SC)

stops.

F	Pin map						
	Pin	Connection					
	1	OE or ST					
	2	GND					
	3	OUT					
	4	VCC					

P	Pin map: SG-8002DC					
	Pin	Connection				
	1	OE or ST				
	4	GND				
	5	OUT				
	8	VCC				

Pį	in map: SG-8002DB					
	Pin	Connection				
	1	OE or ST				
	7	GND				
	8	OUT				
	14	VCC				

To maintain stable operation, provide a 0.01uF to 0.1uF by-pass capacitor at a location as near as possible to the power source terminal of the crystal product (between Vcc - GND).

Products number

(Please contact us for each product.)

SG-8002CE: Q3321CExxxxxx00 SG-8002JC: Q3307JCx1xxxx00 SG-8002LB: Q3323LBxxxxxx00 SG-8002JA: Q3306JAx1xxxx00 SG-8002CA: Q3204DCx1xxxx00 Q3309CAx0xxxx00 SG-8002DC: SG-8002JF: Q3308JFx1xxxx00 SG-8002DB: Q3203DBx1xxxx00



SG-8002 Series Outline of specifications

Mod	el	Supply volt- age	Operating temperature	Output load condition		Symmetry		Output rise time / Output fall time
	PT/ST	4.5 V to	-20 °C to +70 °C -40 °C to +85 °C	5TTL+15pF	40 % to 60 % 45 % to 55 % 45 % to 55 %	(1.4 V, L_TTL=5 TTL+15 pF, f0≤125 MHz) (1.4 V, L_TTL=5 TTL+15 pF, f0≤66.7 MHz) (1.4 V, L_TTL=5 TTL+15 pF, f0≤27.0 MHz)	2.0 ns Max. 4.0 ns Max.	(
SG-8002CE	PH/SH	5.5 V	-20 °C to +70 °C -40 °C to +85 °C	15 pF (f0≤125 MHz) 25 pF (f0≤100 MHz) 25 pF (f0≤27 MHz)	40 % to 60 % 45 % to 55 % 45 % to 55 %	(50 % VCC, L_CMOS=15 pF, f0≤125 MHz) (50 % VCC, L_CMOS=25 pF, f0≤66.7 MHz) (50 % VCC, L_CMOS=25 pF, f0≤27.0 MHz)	3.0 ns Max.	(20 % VCC to 80 % VCC,L_CMOS=Max.)
	PC/SC	3.0 V to 3.6 V 2.7 V to 3.6 V		15 pF	40 % to 60 % 45 % to 55 % 40 % to 60 %	(50 % VCC, L_CMOS=15 pF, f0≤125 MHz) (50 % VCC, L_CMOS=15 pF, f0≤40 MHz) (50 % VCC, L_CMOS=15 pF, f0≤66.7 MHz)	3.0 ns Max.	(20 % VCC to 80 % VCC,L_CMOS=Max.)
	PH/SH	4.5 V to 5.5 V	-40 °C to +85 °C	15 pF 25pF (f0≤50 MHz)	40 % to 60 % 45 % to 55 %	(50 % VCC, L_CMOS=15 pF, f0≤80 MHz) (50 % VCC, L_CMOS=25 pF, f0≤50 MHz)	3.0 ns Max.	(20 % VCC to 80 % VCC,L_CMOS=Max.)
SG-8002LB	PC/SC	3.0 V to 3.6 V 2.7 V to 3.6 V	-40 °C to +85 °C	15 pF	40 % to 60 % 45 % to 55 % 40 % to 60 %	(50 % VCC, L_CMOS=15 pF, f0≤125 MHz) (50 % VCC, L_CMOS=15 pF, f0≤40 MHz) (50 % VCC, L_CMOS=15 pF, f0≤66.7 MHz)	-3.0 ns Max.	(20 % VCC to 80 % VCC,L_CMOS=Max.)
	PT/ST		-20 °C to +70 °C -40 °C to +85 °C	5TTL+15 pF (f0≤ 90 MHz) 15 pF (f0≤125 MHz) 25 pF (f0≤66.7 MHz) 15 pF (f0≤40 MHz)	40 % to 60 % ↑ 45 % to 55 % 40 % to 60 %	(1.4 V, L_TTL=5 TTL+15 pF, f0≤90 MHz) (1.4 V, L_CMOS=15 pF, f0≤125 MHz) (1.4 V, L_CMOS=25 pF, f0≤66.7 MHz) (1.4 V, L_TTL=5 TTL+15 pF, f0≤66.7 MHz) (1.4 V, L_CMOS=15 pF, f0≤40 MHz)		(0.8 V to 2.0 V,L_CMOS≤25pF) (0.4 V to 2.4 V,L_CMOS or L_TTL=Max.)
SG-8002JF	PH/SH	5.5 V	-20 °C to +70 °C	15 pF (f0≤125 MHz) 25 pF (f0≤90 MHz) 50 pF (f0≤50 MHz) 15 pF (f0≤40 MHz)	40 % to 60 % ↑ 45 % to 55 % 40 % to 60 %			(20 % VCC to 80 % VCC,L_CMOS≤25pF) (20 % VCC to 80 % VCC,L_CMOS=Max.)
	PC/SC	3.0 V to 3.6 V 2.7 V to 3.6 V	-40 °C to ±85 °C	15 pF 30 pF (f0≤40 MHz) 15 pF	40 % to 60 % 45 % to 55 % 40 % to 60 %	(50 % VCC, CL=15 pF, f0≤125 MHz) (50 % VCC, CL=30 pF, f0≤40 MHz) (50 % VCC, CL=30 pF, f0≤40 MHz)		(20 % VCC to 80 % VCC,L_CMOS≤15pF) (20 % VCC to 80 % VCC,L_CMOS=Max.)
SG-8002CA	PT/ST	3.0 V	-20 °C to +70 °C	5TTL+15pF (f0≤125 MHz) 25 pF (f0≤66.7 MHz) 5 TTL+15 pF (f0≤40 MHz)	↑ 45 % to 55 %	(1.4 V, L_CMOS=25 pF, f0≤66.7 MHz)		(0.8 V to 2.0 V,L_CMOS or L_TTL=Max.) (0.4 V to 2.4 V,L_CMOS or L_TTL=Max.)
SG-8002CA		4.5 V to	-40 °C to +85 °C	15 pF (f0≤55 MHz)	45 % to 55 % 40 % to 60 %	(1.4 V, L_TTL=5 TTL+15 pF, f0≤40.0 MHz)		
SG-8002DB	PH/SH	0.0 1	-20 °C to +70 °C	25 pF (f0≤125 MHz) 50 pF (f0≤66.7 MHz) 15 pF (f0≤55 MHz)	15 % to 55 % 45 % to 55 % 40 % to 60 %	(50 % VCC, L_CMOS=50 pF, f0≤66.7 MHz) (50 % VCC, L_CMOS=25 pF, f0≤66.7 MHz) (50 % VCC, L_CMOS=15 pF, f0≤55.0 MHz)		(20 % VCC to 80 % VCC,L_CMOS≤25pF) (20 % VCC to 80 % VCC,L_CMOS=Max.)
SG-8002DC		3.0 V to	-40 °C to +85 °C	25 pF (f0≤40 MHz) 15 pF	45 % to 55 % 40 % to 60 %	(50 % VCC, L_MOS=15 pF, f0≤95.0 MHz) (50 % VCC, L_MOS=25 pF, f0≤40.0 MHz) (50 % VCC, L_CMOS=15 pF, f0≤125 MHz)		
	PC/SC	3.6 V 2.7 V to 3.6 V	-40 °C to +85 °C	30 pF (f0≤40 MHz) 15 pF	45 % to 55 % 40 % to 60 %	(50 % VCC, L_CMOS=30 pF, f0≤40 MHz) (50 % VCC, L_CMOS=15 pF, f0≤66.7 MHz)		(20 % VCC to 80 % VCC,L_CMOS≤15pF) (20 % VCC to 80 % VCC,L_CMOS=Max.)
SG-8002JC	PT/ST	4.5 V to -20 °C to	20.90 to .70.00	5TTL+15 pF (f0≤90 MHz) 15 pF (f0≤125 MHz) 25 pF (f0≤66.7 MHz)	40 % to 60 % ↑ 45 % to 55 %	(1.4 V,L_CMOS=15 pF, f0≤125 MHz) (1.4 V,L_TTL=5 TTL+15 pF, f0≤90.0 MHz) (1.4 V,L_CMOS=25 pF, f0≤66.7 MHz) (1.4 V,L_TTL=5 TTL+15 pF, f0≤66.7 MHz)		(0.8 V to 2.0 V,L_CMOS or L_TTL=Max.) (0.4 V to 2.4 V,L_CMOS or L_TTL=Max.)
	PH/SH		-20 °C to +70 °C	15 pF (f0≤125 MHz) 25 pF (f0≤90 MHz) 50 pF (f0≤66.7 MHz)	40 % to 60 % ↑ 45 % to 55 %	(50 % VCC, L_CMOS=15 pF, f0≤125 MHz) (50 % VCC, L_CMOS=25 pF, f0≤90 MHz) (50 % VCC, L_CMOS=50 pF, f0≤50 MHz) (50 % VCC, L_CMOS=25 pF, f0≤66.7 MHz)		(20 % VCC to 80 % VCC,L_CMOS≤25pF) (20 % VCC to 80 % VCC,L_CMOS=Max.)
	PC/SC	3.0 V to 3.6 V 2.7 V to 3.6 V	-20 °C to +70 °C	15 pF 30 pF (f0≤40 MHz) 15 pF	40 % to 60 % 45 % to 55 % 40 % to 60 %	(50 % VCC, L_CMOS=15 pF, f0≤125 MHz) (50 % VCC, L_CMOS=30 pF, f0≤40 MHz) (50 % VCC, L_CMOS=15 pF, f0≤66.7 MHz)		(20 % VCC to 80 % VCC,L_CMOS≤15pF) (20 % VCC to 80 % VCC,L_CMOS=Max.)

► TABLE OF FREQUENCY RANGE

Model		Supply voltage	Frequency	Frequency tolerance Operating Temperature	
	PT/ ST	4.5 V to 5.5 V	1.0 MHz to 125 MHz	B,C	
SG-8002CE	PH/ SH	4.5 V 10 5.5 V	1.0 MHz to 27 MHz	M	
3G-0002CL	PC/SC	3.0 V to 3.6 V	1.0 MHz to 125 MHz	B,C,M	
	FC/3C	2.7 V to 3.6 V	1.0 MHz to 66.7 MHz	D,C,IVI	
	PH/ SH	4.5 V to 5.5 V	1.0 MHz to 80 MHz	B,C	
SG-8002LB	FH/ SH	4.5 V 10 5.5 V	1.0 MHz to 27 MHz	M,L	
3G-0002LB	PC/SC	3.0 V to 3.6 V	1.0 MHz to 125 MHz	B,C,M,L	
	FC/ 3C	2.7 V to 3.6 V	1.0 MHz to 66.7 MHz	B,C,IVI,L	
	PT/ ST	4.5 V to 5.5 V	1.0 MHz to 125 MHz	B,C	
SG-8002JF	PH/ SH		1.0 MHz to 40 MHz	M	
3G-00023F	PC/ SC	3.0 V to 3.6 V	1.0 MHz to 125 MHz	B,C,M	
		2.7 V to 3.6 V	1.0 MHz to 66.7 MHz		
SG-8002CA	PT/ ST	4.5 V to 5.5 V	1.0 MHz to 125 MHz	B,C	
SG-8002JA	PH/ SH	4.5 V 10 5.5 V	1.0 MHz to 55 MHz	M	
SG-8002DB	PC/ SC	3.0 V to 3.6 V	1.0 MHz to 125 MHz	B,C,M	
SG-8002DC		2.7 V to 3.6 V	1.0 MHz to 66.7 MHz		
SG-8002JC	PT/ ST PH/ SH	4.5 V to 5.5 V	1.0 MHz to 125 MHz	В,С	
30-000230	PC/SC	3.0 V to 3.6 V	1.0 MHz to 125 MHz	B,C	
	1 0/ 00	2.7 V to 3.6 V	1.0 MHz to 66.7 MHz	Б,О	

Frequency tolerance: B:±50×10⁻⁶(-20 °C to +70 °C), C:±100×10⁻⁶ (-20 °C to +70 °C), M:±100×10⁻⁶ (-40 °C to +85 °C), L:±50×10⁻⁶ (-40 °C to +85 °C)

SG-8002 series Jitter specifications and characteristics chart

■PLL-PLL connection

Because we use a PLL technology, there are a few cases that the jitter value will increase when SG-8002 is connected to another PLL-oscillator.

In our experience, we are unable to recommend these products for the applications such as telecom carrier use or analog video clock use. Please be careful checking in advance for these application (Jitter specification is Max.250 ps/CL=15 pF)

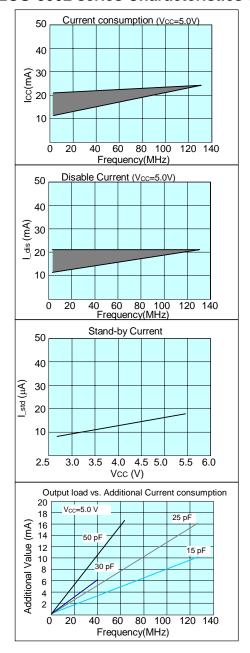
Jitter Specifications

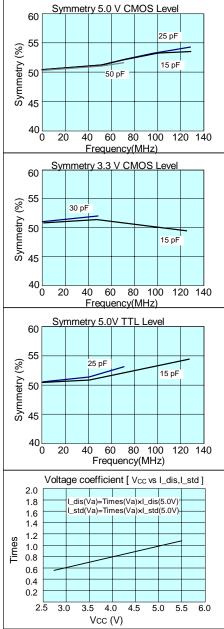
Model	Supply Voltage	Jitter Item	Specifications	Remarks
PT / PH ST / SH	5.0 V ±0.5 V	Cycle to cycle	150 ps Max.	33 MHz \leq f ₀ \leq 125 MHz, L_CMOS=15 pF
			200 ps Max.	1.0 MHz \leq f ₀ $<$ 33 MHz, L_CMOS=15 pF
		Peak to peak	200 ps Max.	33 MHz \leq f ₀ \leq 125 MHz, L_CMOS=15 pF
			250 ps Max.	1.0 MHz ≤ fo < 33 MHz, L_CMOS=15 pF
SC / PC	3.3 V ±0.3 V	Cycle to cycle	200 ps Max.	$1.0 \text{ MHz} \le f_0 \le 125 \text{ MHz}, L_\text{CMOS=15 pF}$
		Peak to peak	250 ps Max.	$1.0 \text{ MHz} \le f_0 \le 125 \text{ MHz}, L_\text{CMOS=15 pF}$

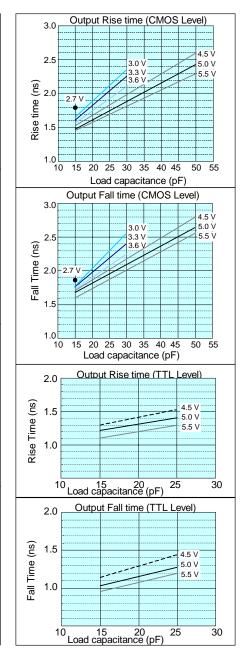
■Remarks on noise management for power supply line

We do not recommend inserting filters or other devices in the power supply line as the counter measure of EMI noise reduction. This device insertion might cause high-frequency impedance high in the power supply line and it affects oscillator stable drive. When this measure is required, please evaluate circuitry and device behavior in the circuit and verify that it will not affect oscillation. Start up time (0 % Vcc to 90 % Vcc) of power source should be more than 150 μs.

■SG-8002 series Characteristics chart







"QMEMS" EPSON TOYOCOM

In order to meet customer needs in a rapidly advancing digital, broadband and ubiquitous society, we are committed to offering products that are one step ahead of the market and a rank above the rest in quality. To achieve our goals, we follow a "3D (three device) strategy" designed to drive both horizontal and vertical growth. We will to grow our three device categories of "Timing Devices", "Sensing Devices" and "Optical Devices", and expand vertical growth through a combination of products from these categories.

A Quartz MEMS is any high added value quartz device that exploits the characteristics of quartz crystal material but that is produced using MEMS (micro-electro-mechanical system) processing technology.

Market needs are advancing faster than previously imagined toward smaller, more stable crystal products, but we will stay ahead of the curve by rolling out products that exceed market speed and quality requirements. We want to further accelerate the 3D strategy by QMEMS.

Quartz devices have become crucial in the network environment where products are increasingly intended for broadband, ubiquitous applications

and where various types of terminals can transfer information almost immediately via LAN and WAN on a global scale. Epson Toyocom Corporation addresses every single aspect within a network environment. The new corporation offers "Digital Convergence" solutions to problems arising with products for consumer use, such as, core network systems and automotive systems.



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PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

At Epson Toyocom, all environmental initiatives operate under the Plan-Do-Check-Action(PDCA) cycle designed to achieve continuous improvements. The environmental management system (EMS) operates under the ISO 14001 environmental management standard.

All of our major manufacturing and non-manufacturing sites,in Japan and overseas, completed the acquisition of ISO 14001 certification.

ISO 14000 is an international standard for environmental management that was established by the International Standards Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.

WORKING FOR HIGH QUALITY

In order provide high quality and reliable products and services than meet customer needs.

Epson Toyocom made early efforts towards obtaining ISO9000 series certification and has acquired ISO9001 for all business establishments in Japan and abroad. We have also acquired ISO/TS 16949 certification that is requested strongly by major automotive manufacturers as standard.

ISO/TS16949 is the international standard that added the sector-specific supplemental requirements for automotive industry based on ISO9001.

► Explanation of the mark that are using it for the catalog



►Pb free.



► Complies with EU RoHS directive.

*About the products without the Pb-free mark.

Contains Pb in products exempted by EU RoHS directive.

(Contains Pb in sealing glass, high melting temperature type solder or other.)



▶ The products have been designed for high reliability applications such as Automotive.

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 of mass destruction or for other military purposes. You are also requested that you would not make the products available to any third party
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